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JP 2003504846 W 20030204 (200320) 13p H05K003-28

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AB DE 19930782 A UPAB: 20010220

NOVELTY - Process for treating the surface of a ceramic-hybrid substrate having ceramic surface regions and metallic surface regions comprises esterifying the ceramic surface.

DETAILED DESCRIPTION - Preferred Features: The ceramic surface regions are treated with a solution containing organic components. The ceramic structure is based on silicon and the solution is a siloxane solution.

USE - Used in the production of electrical circuits, e.g. in a vehicle electronic system for controlling the engine and antiblock control.

 $\ensuremath{\mathsf{ADVANTAGE}}$ - Short circuits between neighboring metallic surface regions are avoided.

Dwg.0/5

FS CPI

FA AB

MC CPI: L02-G07; L03-H04E5; L03-J